

< High-power GaAs FET (small signal gain stage) >

# **MGF0909A**

L & S BAND / 6W non - matched

### DESCRIPTION

The MGF0909A GaAs FET with an N-channel schottky Gate, is designed for use L/S band amplifiers.

#### FEATURES

- High output power
- P1dB=38.0dBm(TYP.) @f=2.3GHz • High power gain
  - GLp=11.0dB(TYP.) @f=2.3GHz
- High power added efficiency ηadd=45%(TYP.) @f=2.3GHz,P1dB
- Hermetic Package

#### APPLICATION

• For L/S Band power amplifiers

#### QUALITY

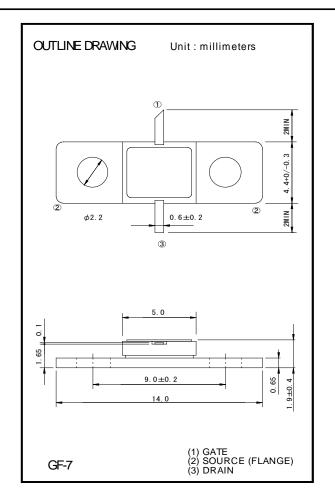
• GG

#### **RECOMMENDED BIAS CONDITIONS**

• Vds=10V • Ids=1.3A • Rg=100 $\Omega$ 

#### Absolute maximum ratings (Ta=25°C)

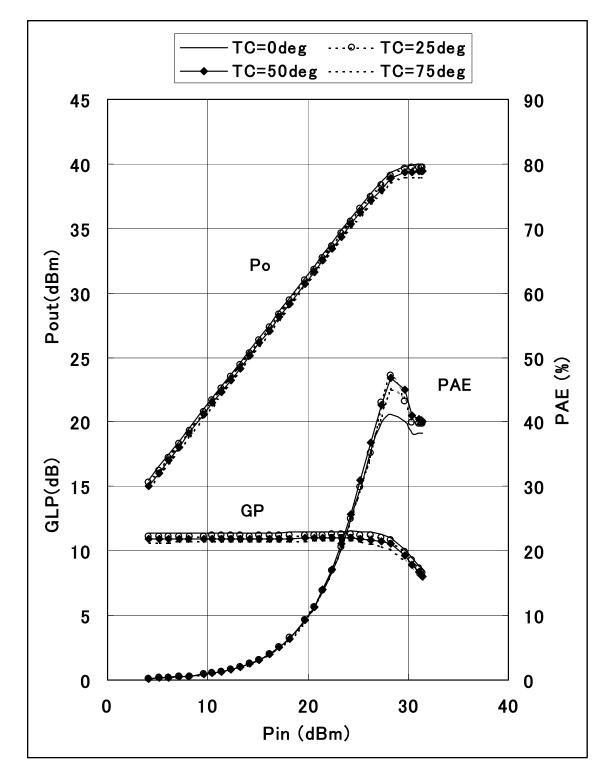
Symbol	Parameter	Ratings	Unit
VGSO	Gate to sourcebreakdown voltage	-15	V
VGDO	Gate to drain breakdown voltage	-15	V
ID	Drain current	5	А
IGR	Reverse gate current	-15	mA
IGF	Forward gate current	31.5	mA
PT	Total power dissipation	27.3	W
Tch	Cannel temperature	175	°C
Tstg	Storage temperature	-65 to +175	°C



#### Electrical characteristics (Ta=25°C)

Symbol	Parameter	Test conditions	Limits		Unit	
			Min.	Тур.	Max.	
IDSS	Saturated drain current	VDS=3V,VGS=0V	-		5.0	А
VGS(off)	Gate to source cut-off voltage	VDS=3V,ID=10mA	-2.0	-	-5.0	V
gm	Transconductance	VDS=3V,ID=1.3A	-	1.5	-	S
P1dB	Output power 1dB Compression P	VDS=10V,ID=1.3A,f=2.3GHz	37.0	38.0	-	dBm
ηadd	Power added Efficiency *1	*1:Po=P1dB	-	45	-	%
GLP	Linear Power Gain *2	*2:Pi=22dBm	10.0	11.0	-	dB
Rth(ch-c)	Thermal Resistance *1	∆Vf Method	-	-	9	°C/W

\*1:Channel to case / Above parameters, ratings, limits are subject to change.



## MGF0909A TYPICAL CHARACTERISTICS Tc=0/25/50/75deg.C

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